



Product Change Notification: DSNO-10JHUT663

Date:

19-Sep-2024

Product Category:

8-Bit Microcontrollers

Notification Subject:

CCB 7041 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected ATTINY16x, ATTINY204, ATTINY214, ATTINY322, ATTINY4x, ATTINY8x, ABR16EB14, PIC16F131, PIC16F152, PIC16F171, PIC16F180 and PIC16F181 device families available in 14L SOIC (.150in) package at MTAI assembly site.

Affected CPNs:

[DSNO-10JHUT663_Affected_CPN_09192024.pdf](#)
[DSNO-10JHUT663_Affected_CPN_09192024.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected ATTINY16x, ATTINY204, ATTINY214, ATTINY322, ATTINY4x, ATTINY8x, ABR16EB14, PIC16F131, PIC16F152, PIC16F171, PIC16F180 and PIC16F181 device families available in 14L SOIC (.150in) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ)

		(MTAI)	
Wire Material	Au	Au	CuPdAu
Die Attach Material	8390A	8390A	
Molding Compound Material	G600V	G600V	
Lead-Frame Material	A194	A194	

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity and on-time delivery performance by qualifying palladium coated copper with gold flash (CuPdAu) as an additional bond wire material at MTAI assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 14 November 2024 (date code: 2446)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	June 2024					>	September 2024					>	November 2024				
Work Week	22	23	24	25	26		36	37	38	39	40		44	45	46	47	48
Initial PCN Issue Date			x														
Qual Report Availability									x								
Final PCN Issue Date									x								

[illegible]

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 14, 2024: Issued initial notification.

June 19, 2024: Reissued the initial notification to correct typographical error in the Notification Subject.

September 19, 2024: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on November 14, 2024.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-10JHUT663_Qual_Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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